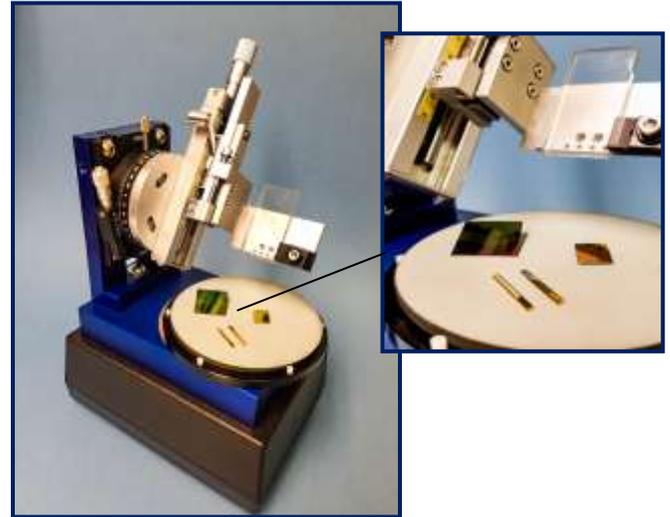


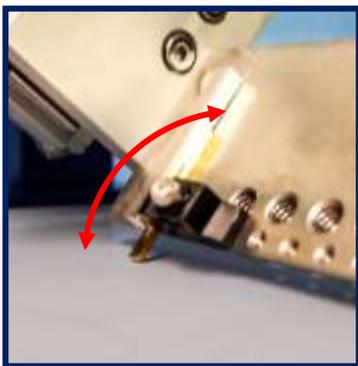
- PROCESSES WAVEGUIDES AND OPTICAL CHIPS**
- ADJUSTABLE FOR VARYING DIMENSIONS**
- FLAT OR ANGLE POLISHING**
- SLIDE AND GUIDE™ COMPONENT HOLDING WITHOUT WAX OR EPOXY**
- BARE FIBER POLISHING UPGRADE OPTION**



SPECIFICATIONS AND FEATURES

FLex™ is designed for the cost-effective processing of waveguides, PLCs, optical chips, and fiber arrays. Its universal carrier secures a variety of component dimensions using the unique “Slide and Guide™” locking mechanism.

Components can be polished with either flat or angled edges. Polishing is controlled via precision linear translation and adjustable pressure application. This produces consistent and repeatable polish yields.



The polishing angle is adjustable for specialized applications.



FLex’s universal carrier supports a variety of component dimensions and does not require wax or holding compounds.

An optional mounting fixture with fiber adapters can upgrade FLex™ for bare fiber polishing applications.

Operational

Component Support

Waveguides, planar lightwave circuits, optical chips, fiber arrays

Component Dimension Range¹

Width: 5mm to 25mm
Thickness: 0.5mm to 5mm
Length: >5mm

Polishing Tolerance

+/-0.3 degree (X/Y axis along edge)

Adjustable Polish Angle Range¹

0 deg. (flat) to 45 deg.

Polishing Films

4 inch diameter

Polishing Motion

Random orbital

Timer

User adjustable, digital cycle timing

Power

AC adapter/9 volt battery

Size and Weight

7”x 4.5” footprint
4.5 lbs

¹ Custom dimensions and angles available.

